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Understanding <u>Embedded - FPGAs (Field Programmable Gate Array)</u>

Embedded - FPGAs, or Field Programmable Gate Arrays, are advanced integrated circuits that offer unparalleled flexibility and performance for digital systems. Unlike traditional fixed-function logic devices, FPGAs can be programmed and reprogrammed to execute a wide array of logical operations, enabling customized functionality tailored to specific applications. This reprogrammability allows developers to iterate designs quickly and implement complex functions without the need for custom hardware.

Applications of Embedded - FPGAs

The versatility of Embedded - FPGAs makes them indispensable in numerous fields. In telecommunications.

Details	
Product Status	Active
Number of LABs/CLBs	250540
Number of Logic Elements/Cells	660000
Total RAM Bits	49610752
Number of I/O	696
Number of Gates	-
Voltage - Supply	0.87V ~ 0.98V
Mounting Type	Surface Mount
Operating Temperature	-40°C ~ 100°C (TJ)
Package / Case	1517-BBGA, FCBGA
Supplier Device Package	1517-FCBGA (40x40)
Purchase URL	https://www.e-xfl.com/product-detail/intel/10ax066k2f40i2lg

Email: info@E-XFL.COM

Address: Room A, 16/F, Full Win Commercial Centre, 573 Nathan Road, Mongkok, Hong Kong

A10-OVERVIEW | 2018.04.09



Feature		Description						
Embedded Hard IP blocks	Variable-precision DSP	 Native support for signal processing precision levels from 18 x 19 to 54 x 54 Native support for 27 x 27 multiplier mode 64-bit accumulator and cascade for systolic finite impulse responses (FIRs) Internal coefficient memory banks Preadder/subtractor for improved efficiency Additional pipeline register to increase performance and reduce power Supports floating point arithmetic: Perform multiplication, addition, subtraction, multiply-add, multiply-subtract, and complex multiplication. Supports multiplication with accumulation capability, cascade summation, and cascade subtraction capability. Dynamic accumulator reset control. Support direct vector dot and complex multiplication chaining multiply floating point DSP blocks. 						
	Memory controller	DDR4, DDR3, and DDR3L						
	PCI Express*	PCI Express (PCIe*) Gen3 (x1, x2, x4, or x8), Gen2 (x1, x2, x4, or x8) and Gen1 (x1, x2, x4, or x8) hard IP with complete protocol stack, endpoint, and root port						
	Transceiver I/O	10GBASE-KR/40GBASE-KR4 Forward Error Correction (FEC) PCS hard IPs that support:						
Core clock networks	 667 MHz externa 800 MHz LVDS in Global, regional, and 	c clocking, depending on the application: I memory interface clocking with 2,400 Mbps DDR4 interface terface clocking with 1,600 Mbps LVDS interface I peripheral clock networks are not used can be gated to reduce dynamic power						
Phase-locked loops (PLLs)	High-resolution fractional synthesis PLLs: Precision clock synthesis, clock delay compensation, and zero delay buffering (ZDB) Support integer mode and fractional mode Fractional mode support with third-order delta-sigma modulation Integer PLLs: Adjacent to general purpose I/Os Support external memory and LVDS interfaces							
FPGA General-purpose I/Os (GPIOs)	On-chip termination	1.6 Gbps LVDS—every pair can be configured as receiver or transmitter On-chip termination (OCT) 1.2 V to 3.0 V single-ended LVTTL/LVCMOS interfacing						
External Memory Interface	DDR4—speeds upDDR3—speeds up	oller— DDR4, DDR3, and DDR3L support to 1,200 MHz/2,400 Mbps to 1,067 MHz/2,133 Mbps to 1,067 MHz/2,133 Mbps to 1,067 MHz/2,134 Mhz/2,134 Mbps to 1,067 Mhz/2,134						



Feature	Description
	 Dynamic reconfiguration of the transceivers and PLLs Fine-grained partial reconfiguration of the core fabric Active Serial x4 Interface
Power management	SmartVID Low static power device options Programmable Power Technology Intel Quartus Prime integrated power analysis
Software and tools	 Intel Quartus Prime design suite Transceiver toolkit Platform Designer system integration tool DSP Builder for Intel FPGAs OpenCL™ support Intel SoC FPGA Embedded Design Suite (EDS)

Related Information

Intel Arria 10 Transceiver PHY Overview

Provides details on Intel Arria 10 transceivers.

Intel Arria 10 Device Variants and Packages

Table 4. **Device Variants for the Intel Arria 10 Device Family**

Variant	Description
Intel Arria 10 GX	FPGA featuring 17.4 Gbps transceivers for short reach applications with 12.5 backplane driving capability.
Intel Arria 10 GT	 FPGA featuring: 17.4 Gbps transceivers for short reach applications with 12.5 backplane driving capability. 25.8 Gbps transceivers for supporting CAUI-4 and CEI-25G applications with CFP2 and CFP4 modules.
Intel Arria 10 SX	SoC integrating ARM-based HPS and FPGA featuring 17.4 Gbps transceivers for short reach applications with 12.5 backplane driving capability.

Intel Arria 10 GX

This section provides the available options, maximum resource counts, and package plan for the Intel Arria 10 GX devices.

The information in this section is correct at the time of publication. For the latest information and to get more details, refer to the Intel FPGA Product Selector.

Related Information

Intel FPGA Product Selector

Provides the latest information on Intel products.



Available Options

Figure 1. Sample Ordering Code and Available Options for Intel Arria 10 GX Devices



Related Information

Transceiver Performance for Intel Arria 10 GX/SX Devices

Provides more information about the transceiver speed grade.



Maximum Resources

Table 5. Maximum Resource Counts for Intel Arria 10 GX Devices (GX 160, GX 220, GX 270, GX 320, and GX 480)

Resc	ource			Product Line		
		GX 160	GX 220	GX 270	GX 320	GX 480
Logic Elements	(LE) (K)	160	220	270	320	480
ALM		61,510	80,330	101,620	119,900	183,590
Register		246,040	321,320	406,480	479,600	734,360
Memory (Kb) M20K		8,800	11,740	15,000	17,820	28,620
	MLAB	1,050	1,690	2,452	2,727	4,164
Variable-precision DSP Block		156	192	830	985	1,368
18 x 19 Multipli	er	312	384	1,660 1,970		2,736
PLL	Fractional Synthesis	6	6	8	8	12
	I/O	6	6	8	8	12
17.4 Gbps Trans	sceiver	12	12	24	24	36
GPIO (3)		288	288	384	384	492
LVDS Pair (4)		120	120	168	168	222
PCIe Hard IP Bl	ock	1	1	2	2	2
Hard Memory C	ontroller	6	6	8	8	12

 $^{^{(3)}}$ The number of GPIOs does not include transceiver I/Os. In the Intel Quartus Prime software, the number of user I/Os includes transceiver I/Os.

⁽⁴⁾ Each LVDS I/O pair can be used as differential input or output.



Maximum Resources

Table 10. Maximum Resource Counts for Intel Arria 10 GT Devices

Reso	ource	Produc	ct Line	
		GT 900	GT 1150	
Logic Elements (LE) (K)		900	1,150	
ALM		339,620	427,200	
Register		1,358,480	1,708,800	
Memory (Kb)	M20K	48,460	54,260	
	MLAB	9,386	12,984	
Variable-precision DSP Block		1,518	1,518	
18 x 19 Multiplier		3,036	3,036	
PLL	Fractional Synthesis	32	32	
	I/O	16	16	
Transceiver	17.4 Gbps	72 ⁽⁵⁾	72 ⁽⁵⁾	
	25.8 Gbps	6	6	
GPIO ⁽⁶⁾		624	624	
LVDS Pair ⁽⁷⁾		312	312	
PCIe Hard IP Block		4	4	
Hard Memory Controller		16	16	

Related Information

Intel Arria 10 GT Channel Usage

Configuring GT/GX channels in Intel Arria 10 GT devices.

Package Plan

Table 11. Package Plan for Intel Arria 10 GT Devices

Refer to I/O and High Speed I/O in Intel Arria 10 Devices chapter for the number of 3 V I/O, LVDS I/O, and LVDS channels in each device package.

Product Line	SF45 (45 mm × 45 mm, 1932-pin FBGA)							
	3 V I/O	LVDS I/O	XCVR					
GT 900	_	624	72					
GT 1150	_	624	72					

⁽⁵⁾ If all 6 GT channels are in use, 12 of the GX channels are not usable.

⁽⁶⁾ The number of GPIOs does not include transceiver I/Os. In the Intel Quartus Prime software, the number of user I/Os includes transceiver I/Os.

⁽⁷⁾ Each LVDS I/O pair can be used as differential input or output.



Related Information

I/O and High-Speed Differential I/O Interfaces in Intel Arria 10 Devices chapter, Intel Arria 10 Device Handbook

Provides the number of 3 V and LVDS I/Os, and LVDS channels for each Intel Arria 10 device package.

Intel Arria 10 SX

This section provides the available options, maximum resource counts, and package plan for the Intel Arria 10 SX devices.

The information in this section is correct at the time of publication. For the latest information and to get more details, refer to the Intel FPGA Product Selector.

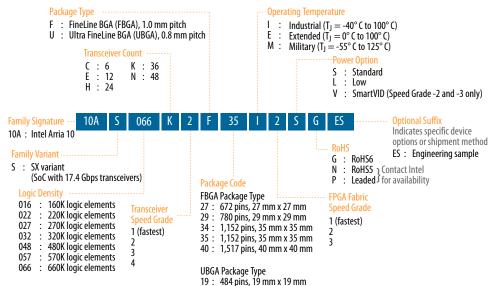
Related Information

Intel FPGA Product Selector

Provides the latest information on Intel products.

Available Options

Figure 3. Sample Ordering Code and Available Options for Intel Arria 10 SX Devices



Related Information

Transceiver Performance for Intel Arria 10 GX/SX Devices

Provides more information about the transceiver speed grade.



Maximum Resources

Table 12. Maximum Resource Counts for Intel Arria 10 SX Devices

Reso	ource			I	Product Line			
		SX 160	SX 220	SX 270	SX 320	SX 480	SX 570	SX 660
Logic Elements	s (LE) (K)	160	220	270	320	480	570	660
ALM		61,510	80,330	101,620	119,900	183,590	217,080	251,680
Register		246,040	321,320	406,480	479,600	734,360	868,320	1,006,720
Memory (Kb)	M20K	8,800	11,740	15,000	17,820	28,620	36,000	42,620
	MLAB	1,050	1,690	2,452	2,727	4,164	5,096	5,788
Variable-precision DSP Block		156	192	830 985		1,368	1,523	1,687
18 x 19 Multip	lier	312	384	1,660	1,970	2,736	3,046	3,374
PLL	Fractional Synthesis	6	6	8	8	12	16	16
	I/O	6	6	8	8	12	16	16
17.4 Gbps Tra	nsceiver	12	12	24	24	36	48	48
GPIO (8)		288	288	384	384	492	696	696
LVDS Pair (9)		120	120	168	168	174	324	324
PCIe Hard IP E	Block	1	1	2	2	2	2	2
Hard Memory	Controller	6	6	8	8	12	16	16
ARM Cortex-As	9 MPCore	Yes	Yes	Yes	Yes	Yes	Yes	Yes

Package Plan

Table 13. Package Plan for Intel Arria 10 SX Devices (U19, F27, F29, and F34)

Refer to I/O and High Speed I/O in Intel Arria 10 Devices chapter for the number of 3 V I/O, LVDS I/O, and LVDS channels in each device package.

Product Line	U19 (19 mm × 19 mm, 484-pin UBGA)				F27 (27 mm × 27 mm, 672-pin FBGA)			F29 (29 mm × 29 mm, 780-pin FBGA)			F34 (35 mm × 35 mm, 1152-pin FBGA)		
	3 V I/O	LVDS I/O	XCVR	3 V I/O	LVDS I/O	XCVR	3 V I/O	LVDS I/O	XCVR	3 V I/O	LVDS I/O	XCVR	
SX 160	48	144	6	48	192	12	48	240	12	_	_	_	
SX 220	48	144	6	48	192	12	48	240	12	_	_	_	
SX 270	_	_	_	48	192	12	48	312	12	48	336	24	
SX 320	_	_	_	48	192	12	48	312	12	48	336	24	
											contii	nued	

 $^{^{(8)}}$ The number of GPIOs does not include transceiver I/Os. In the Intel Quartus Prime software, the number of user I/Os includes transceiver I/Os.

⁽⁹⁾ Each LVDS I/O pair can be used as differential input or output.



Product Line	U19 (19 mm × 19 mm, 484-pin UBGA)		F27 (27 mm × 27 mm, 672-pin FBGA)			F29 (29 mm × 29 mm, 780-pin FBGA)			F34 (35 mm × 35 mm, 1152-pin FBGA)			
	3 V I/O	LVDS I/O	XCVR	3 V I/O			3 V I/O	LVDS I/O	XCVR	3 V I/O	LVDS I/O	XCVR
SX 480	_	_	_	_	_	_	48	312	12	48	444	24
SX 570	_	_	_	_	_	_	_	_	_	48	444	24
SX 660	_	_	_	_	_	_	_	_	_	48	444	24

Table 14. Package Plan for Intel Arria 10 SX Devices (F35, KF40, and NF40)

Refer to I/O and High Speed I/O in Intel Arria 10 Devices chapter for the number of 3 V I/O, LVDS I/O, and LVDS channels in each device package.

Product Line	F35 (35 mm × 35 mm, 1152-pin FBGA)				KF40 mm × 40 n 17-pin FBG		NF40 (40 mm × 40 mm, 1517-pin FBGA)			
	3 V I/O	LVDS I/O	XCVR	3 V I/O	LVDS I/O	XCVR	3 V I/O	LVDS I/O	XCVR	
SX 270	48	336	24	_	_	_	_	_	_	
SX 320	48	336	24	_	_	_	_	_	_	
SX 480	48	348	36	_	_	_	_	_	_	
SX 570	48	348	36	96	600	36	48	540	48	
SX 660	48	348	36	96	600	36	48	540	48	

Related Information

 ${\rm I/O}$ and High-Speed Differential ${\rm I/O}$ Interfaces in Intel Arria 10 Devices chapter, Intel Arria 10 Device Handbook

Provides the number of 3 V and LVDS I/Os, and LVDS channels for each Intel Arria 10 device package.



I/O Vertical Migration for Intel Arria 10 Devices

Figure 4. Migration Capability Across Intel Arria 10 Product Lines

- The arrows indicate the migration paths. The devices included in each vertical migration path are shaded. Devices with fewer resources in the same path have lighter shades.
- To achieve the full I/O migration across product lines in the same migration path, restrict I/Os and transceivers usage to match the product line with the lowest I/O and transceiver counts.
- An LVDS I/O bank in the source device may be mapped to a 3 V I/O bank in the target device. To use
 memory interface clock frequency higher than 533 MHz, assign external memory interface pins only to
 banks that are LVDS I/O in both devices.
- There may be nominal 0.15 mm package height difference between some product lines in the same package type.
- Some migration paths are not shown in the Intel Quartus Prime software Pin Migration View.

Variant	Product						Package	e				
Varialit	Line	U19	F27	F29	F34	F35	KF40	NF40	RF40	NF45	SF45	UF45
	GX 160	1	1	1								
	GX 220	+										
	GX 270				1	1						
	GX 320		V									
Intel® Arria® 10 GX	GX 480			V								
	GX 570						1	1				
	GX 660					V	\					
	GX 900								1	1		1
	GX 1150				V			+	+	+		+
Intel Arria 10 GT	GT 900											
intel Afria 10 G1	GT 1150										V	
	SX 160	1	1	1								
	SX 220	+										
	SX 270				1	†						
Intel Arria 10 SX	SX 320		V									
	SX 480			V								
	SX 570						†	†				
	SX 660				V							

Note:

To verify the pin migration compatibility, use the **Pin Migration View** window in the Intel Quartus Prime software Pin Planner.

Adaptive Logic Module

Intel Arria 10 devices use a 20 nm ALM as the basic building block of the logic fabric.

The ALM architecture is the same as the previous generation FPGAs, allowing for efficient implementation of logic functions and easy conversion of IP between the device generations.

The ALM, as shown in following figure, uses an 8-input fracturable look-up table (LUT) with four dedicated registers to help improve timing closure in register-rich designs and achieve an even higher design packing capability than the traditional two-register per LUT architecture.



Figure 5. ALM for Intel Arria 10 Devices



The Intel Quartus Prime software optimizes your design according to the ALM logic structure and automatically maps legacy designs into the Intel Arria 10 ALM architecture.

Variable-Precision DSP Block

The Intel Arria 10 variable precision DSP blocks support fixed-point arithmetic and floating-point arithmetic.

Features for fixed-point arithmetic:

- · High-performance, power-optimized, and fully registered multiplication operations
- 18-bit and 27-bit word lengths
- Two 18 x 19 multipliers or one 27 x 27 multiplier per DSP block
- Built-in addition, subtraction, and 64-bit double accumulation register to combine multiplication results
- Cascading 19-bit or 27-bit when pre-adder is disabled and cascading 18-bit when pre-adder is used to form the tap-delay line for filtering applications
- Cascading 64-bit output bus to propagate output results from one block to the next block without external logic support
- Hard pre-adder supported in 19-bit and 27-bit modes for symmetric filters
- Internal coefficient register bank in both 18-bit and 27-bit modes for filter implementation
- 18-bit and 27-bit systolic finite impulse response (FIR) filters with distributed output adder
- Biased rounding support

A10-OVERVIEW | 2018.04.09



Features for floating-point arithmetic:

- A completely hardened architecture that supports multiplication, addition, subtraction, multiply-add, and multiply-subtract
- Multiplication with accumulation capability and a dynamic accumulator reset control
- Multiplication with cascade summation capability
- Multiplication with cascade subtraction capability
- Complex multiplication
- Direct vector dot product
- Systolic FIR filter

Table 15. Variable-Precision DSP Block Configurations for Intel Arria 10 Devices

Usage Example	Multiplier Size (Bit)	DSP Block Resources
Medium precision fixed point	Two 18 x 19	1
High precision fixed or Single precision floating point	One 27 x 27	1
Fixed point FFTs	One 19 x 36 with external adder	1
Very high precision fixed point	One 36 x 36 with external adder	2
Double precision floating point	One 54 x 54 with external adder	4

Table 16. Resources for Fixed-Point Arithmetic in Intel Arria 10 Devices

The table lists the variable-precision DSP resources by bit precision for each Intel Arria 10 device.

Variant	ariant Product Line Variable- precision DSP Block		Independent Input and Output Multiplications Operator		18 x 19 Multiplier Adder Sum	18 x 18 Multiplier Adder
		DSP BIOCK	18 x 19 Multiplier	27 x 27 Multiplier	Mode Mode	Summed with 36 bit Input
AIntel Arria 10	GX 160	156	312	156	156	156
GX	GX 220	192	384	192	192	192
	GX 270	830	1,660	830	830	830
	GX 320	984	1,968	984	984	984
	GX 480	1,368	2,736	1,368	1,368	1,368
	GX 570	1,523	3,046	1,523	1,523	1,523
	GX 660	1,687	3,374	1,687	1,687	1,687
	GX 900	1,518	3,036	1,518	1,518	1,518
	GX 1150	1,518	3,036	1,518	1,518	1,518
Intel Arria 10 GT	GT 900	1,518	3,036	1,518	1,518	1,518
GI	GT 1150	1,518	3,036	1,518	1,518	1,518
Intel Arria 10	SX 160	156	312	156	156	156
SX	SX 220	192	384	192	192	192
	SX 270	830	1,660	830	830	830
						continued



Embedded Memory Configurations for Single-port Mode

Table 19. Single-port Embedded Memory Configurations for Intel Arria 10 Devices

This table lists the maximum configurations supported for single-port RAM and ROM modes.

Memory Block	Depth (bits)	Programmable Width
MLAB	32	x16, x18, or x20
	64 (10)	x8, x9, x10
M20K	512	x40, x32
	1K	x20, x16
	2K	x10, x8
	4K	x5, x4
	8K	x2
	16K	x1

Clock Networks and PLL Clock Sources

The clock network architecture is based on Intel's global, regional, and peripheral clock structure. This clock structure is supported by dedicated clock input pins, fractional clock synthesis PLLs, and integer I/O PLLs.

Clock Networks

The Intel Arria 10 core clock networks are capable of up to 800 MHz fabric operation across the full industrial temperature range. For the external memory interface, the clock network supports the hard memory controller with speeds up to 2,400 Mbps in a quarter-rate transfer.

To reduce power consumption, the Intel Quartus Prime software identifies all unused sections of the clock network and powers them down.

Fractional Synthesis and I/O PLLs

Intel Arria 10 devices contain up to 32 fractional synthesis PLLs and up to 16 I/O PLLs that are available for both specific and general purpose uses in the core:

- Fractional synthesis PLLs—located in the column adjacent to the transceiver blocks
- I/O PLLs-located in each bank of the 48 I/Os

Fractional Synthesis PLLs

You can use the fractional synthesis PLLs to:

- Reduce the number of oscillators that are required on your board
- Reduce the number of clock pins that are used in the device by synthesizing multiple clock frequencies from a single reference clock source

⁽¹⁰⁾ Supported through software emulation and consumes additional MLAB blocks.

A10-OVERVIEW | 2018.04.09



The fractional synthesis PLLs support the following features:

- Reference clock frequency synthesis for transceiver CMU and Advanced Transmit (ATX) PLLs
- Clock network delay compensation
- Zero-delay buffering
- Direct transmit clocking for transceivers
- Independently configurable into two modes:
 - Conventional integer mode equivalent to the general purpose PLL
 - Enhanced fractional mode with third order delta-sigma modulation
- PLL cascading

I/O PLLs

The integer mode I/O PLLs are located in each bank of 48 I/Os. You can use the I/O PLLs to simplify the design of external memory and high-speed LVDS interfaces.

In each I/O bank, the I/O PLLs are adjacent to the hard memory controllers and LVDS SERDES. Because these PLLs are tightly coupled with the I/Os that need to use them, it makes it easier to close timing.

You can use the I/O PLLs for general purpose applications in the core such as clock network delay compensation and zero-delay buffering.

Intel Arria 10 devices support PLL-to-PLL cascading.

FPGA General Purpose I/O

Intel Arria 10 devices offer highly configurable GPIOs. Each I/O bank contains 48 general purpose I/Os and a high-efficiency hard memory controller.

The following list describes the features of the GPIOs:

- Consist of 3 V I/Os for high-voltage application and LVDS I/Os for differential signaling
 - $-\$ Up to two 3 V I/O banks, available in some devices, that support up to 3 V I/O standards
 - LVDS I/O banks that support up to 1.8 V I/O standards
- Support a wide range of single-ended and differential I/O interfaces
- LVDS speeds up to 1.6 Gbps
- Each LVDS pair of pins has differential input and output buffers, allowing you to configure the LVDS direction for each pair.
- Programmable bus hold and weak pull-up
- Programmable differential output voltage (V_{OD}) and programmable pre-emphasis



- Series (R_S) and parallel (R_T) on-chip termination (OCT) for all I/O banks with OCT calibration to limit the termination impedance variation
- On-chip dynamic termination that has the ability to swap between series and parallel termination, depending on whether there is read or write on a common bus for signal integrity
- Easy timing closure support using the hard read FIFO in the input register path, and delay-locked loop (DLL) delay chain with fine and coarse architecture

External Memory Interface

Intel Arria 10 devices offer massive external memory bandwidth, with up to seven 32-bit DDR4 memory interfaces running at up to 2,400 Mbps. This bandwidth provides additional ease of design, lower power, and resource efficiencies of hardened high-performance memory controllers.

The memory interface within Intel Arria 10 FPGAs and SoCs delivers the highest performance and ease of use. You can configure up to a maximum width of 144 bits when using the hard or soft memory controllers. If required, you can bypass the hard memory controller and use a soft controller implemented in the user logic.

Each I/O contains a hardened DDR read/write path (PHY) capable of performing key memory interface functionality such as read/write leveling, FIFO buffering to lower latency and improve margin, timing calibration, and on-chip termination.

The timing calibration is aided by the inclusion of hard microcontrollers based on Intel's Nios® II technology, specifically tailored to control the calibration of multiple memory interfaces. This calibration allows the Intel Arria 10 device to compensate for any changes in process, voltage, or temperature either within the Intel Arria 10 device itself, or within the external memory device. The advanced calibration algorithms ensure maximum bandwidth and robust timing margin across all operating conditions.

In addition to parallel memory interfaces, Intel Arria 10 devices support serial memory technologies such as the Hybrid Memory Cube (HMC). The HMC is supported by the Intel Arria 10 high-speed serial transceivers which connect up to four HMC links, with each link running at data rates up to 15 Gbps.

Related Information

External Memory Interface Spec Estimator

Provides a parametric tool that allows you to find and compare the performance of the supported external memory interfaces in IntelFPGAs.

Memory Standards Supported by Intel Arria 10 Devices

The I/Os are designed to provide high performance support for existing and emerging external memory standards.



Related Information

Intel Arria 10 Device Datasheet

Lists the memory interface performance according to memory interface standards, rank or chip select configurations, and Intel Arria 10 device speed grades.

PCIe Gen1, Gen2, and Gen3 Hard IP

Intel Arria 10 devices contain PCIe hard IP that is designed for performance and ease-of-use:

- Includes all layers of the PCIe stack—transaction, data link and physical layers.
- Supports PCIe Gen3, Gen2, and Gen1 Endpoint and Root Port in x1, x2, x4, or x8 lane configuration.
- Operates independently from the core logic—optional configuration via protocol (CvP) allows the PCIe link to power up and complete link training in less than 100 ms while the Intel Arria 10 device completes loading the programming file for the rest of the FPGA.
- Provides added functionality that makes it easier to support emerging features such as Single Root I/O Virtualization (SR-IOV) and optional protocol extensions.
- Provides improved end-to-end datapath protection using ECC.
- Supports FPGA configuration via protocol (CvP) using PCIe at Gen3, Gen2, or Gen1 speed.

Related Information

PCS Features on page 30

Enhanced PCS Hard IP for Interlaken and 10 Gbps Ethernet

Interlaken Support

The Intel Arria 10 enhanced PCS hard IP provides integrated Interlaken PCS supporting rates up to 25.8 Gbps per lane.

The Interlaken PCS is based on the proven functionality of the PCS developed for Intel's previous generation FPGAs, which demonstrated interoperability with Interlaken ASSP vendors and third-party IP suppliers. The Interlaken PCS is present in every transceiver channel in Intel Arria 10 devices.

Related Information

PCS Features on page 30

10 Gbps Ethernet Support

The Intel Arria 10 enhanced PCS hard IP supports 10GBASE-R PCS compliant with IEEE 802.3 10 Gbps Ethernet (10GbE). The integrated hard IP support for 10GbE and the 10 Gbps transceivers save external PHY cost, board space, and system power.



Figure 7. Device Chip Overview for Intel Arria 10 GX and GT Devices



Figure 8. Device Chip Overview for Intel Arria 10 SX Devices



PMA Features

Intel Arria 10 transceivers provide exceptional signal integrity at data rates up to 25.8 Gbps. Clocking options include ultra-low jitter ATX PLLs (LC tank based), clock multiplier unit (CMU) PLLs, and fractional PLLs.



Each transceiver channel contains a channel PLL that can be used as the CMU PLL or clock data recovery (CDR) PLL. In CDR mode, the channel PLL recovers the receiver clock and data in the transceiver channel. Up to 80 independent data rates can be configured on a single Intel Arria 10 device.

Table 23. PMA Features of the Transceivers in Intel Arria 10 Devices

Feature	Capability	
Chip-to-Chip Data Rates	1 Gbps to 17.4 Gbps (Intel Arria 10 GX devices) 1 Gbps to 25.8 Gbps (Intel Arria 10 GT devices)	
Backplane Support	Drive backplanes at data rates up to 12.5 Gbps	
Optical Module Support	SFP+/SFP, XFP, CXP, QSFP/QSFP28, CFP/CFP2/CFP4	
Cable Driving Support	SFP+ Direct Attach, PCI Express over cable, eSATA	
Transmit Pre-Emphasis	4-tap transmit pre-emphasis and de-emphasis to compensate for system channel loss	
Continuous Time Linear Equalizer (CTLE)	Dual mode, high-gain, and high-data rate, linear receive equalization to compensate for system channel loss	
Decision Feedback Equalizer (DFE)	7-fixed and 4-floating tap DFE to equalize backplane channel loss in the presence of crosstalk and noisy environments	
Variable Gain Amplifier	Optimizes the signal amplitude prior to the CDR sampling and operates in fixed and adaptive modes	
Altera Digital Adaptive Parametric Tuning (ADAPT)	Fully digital adaptation engine to automatically adjust all link equalization parameters—including CTLE, DFE, and variable gain amplifier blocks—that provide optimal link margin without intervention from user logic	
Precision Signal Integrity Calibration Engine (PreSICE)	Hardened calibration controller to quickly calibrate all transceiver control parameters on power-up, which provides the optimal signal integrity and jitter performance	
Advanced Transmit (ATX) Low jitter ATX (LC tank based) PLLs with continuous tuning range to cover a wid standard and proprietary protocols		
Fractional PLLs On-chip fractional frequency synthesizers to replace on-board crystal oscillators are system cost		
Digitally Assisted Analog CDR Superior jitter tolerance with fast lock time		
Dynamic Partial Reconfiguration	Allows independent control of the Avalon memory-mapped interface of each transceiver channel for the highest transceiver flexibility	
Multiple PCS-PMA and PCS-PLD interface widths 8-, 10-, 16-, 20-, 32-, 40-, or 64-bit interface widths for flexibility of deserialization encoding, and reduced latency		

PCS Features

This table summarizes the Intel Arria 10 transceiver PCS features. You can use the transceiver PCS to support a wide range of protocols ranging from 1 Gbps to 25.8 Gbps.



Protocol	Data Rate (Gbps)	Transceiver IP	PCS Support
CPRI 6.0 (64B/66B)	0.6144 to 10.1376	Native PHY	Enhanced PCS
CPRI 4.2 (8B/10B)	0.6144 to 9.8304	Native PHY	Standard PCS
OBSAI RP3 v4.2	0.6144 to 6.144	Native PHY	Standard PCS
SD-SDI/HD-SDI/3G-SDI	0.143 ⁽¹²⁾ to 2.97	Native PHY	Standard PCS

Related Information

Intel Arria 10 Transceiver PHY User Guide

Provides more information about the supported transceiver protocols and PHY IP, the PMA architecture, and the standard, enhanced, and PCIe Gen3 PCS architecture.

SoC with Hard Processor System

Each SoC device combines an FPGA fabric and a hard processor system (HPS) in a single device. This combination delivers the flexibility of programmable logic with the power and cost savings of hard IP in these ways:

- Reduces board space, system power, and bill of materials cost by eliminating a discrete embedded processor
- Allows you to differentiate the end product in both hardware and software, and to support virtually any interface standard
- Extends the product life and revenue through in-field hardware and software updates

⁽¹²⁾ The 0.143 Gbps data rate is supported using oversampling of user logic that you must implement in the FPGA fabric.



Scheme	Data Width	Max Clock Rate (MHz)	Max Data Rate (Mbps)	Decompression	Design Security ⁽¹ 4)	Partial Reconfiguration (15)	Remote System Update
Fast passive	8 bits	100	3200	Yes	Yes	Yes ⁽¹⁷⁾	PFL IP
parallel (FPP) through CPLD or	16 bits			Yes	Yes		core
external microcontroller	32 bits			Yes	Yes		
Configuration via	16 bits	100	3200	Yes	Yes	Yes ⁽¹⁷⁾	_
HPS	32 bits			Yes	Yes		
Configuration via Protocol [CvP (PCIe*)]	x1, x2, x4, x8 lanes	_	8000	Yes	Yes	Yes ⁽¹⁶⁾	_

You can configure Intel Arria 10 devices through PCIe using Configuration via Protocol (CvP). The Intel Arria 10 CvP implementation conforms to the PCIe 100 ms power-up-to-active time requirement.

SEU Error Detection and Correction

Intel Arria 10 devices offer robust and easy-to-use single-event upset (SEU) error detection and correction circuitry.

The detection and correction circuitry includes protection for Configuration RAM (CRAM) programming bits and user memories. The CRAM is protected by a continuously running CRC error detection circuit with integrated ECC that automatically corrects one or two errors and detects higher order multi-bit errors. When more than two errors occur, correction is available through reloading of the core programming file, providing a complete design refresh while the FPGA continues to operate.

The physical layout of the Intel Arria 10 CRAM array is optimized to make the majority of multi-bit upsets appear as independent single-bit or double-bit errors which are automatically corrected by the integrated CRAM ECC circuitry. In addition to the CRAM protection, the M20K memory blocks also include integrated ECC circuitry and are layout-optimized for error detection and correction. The MLAB does not have ECC.

Power Management

Intel Arria 10 devices leverage the advanced 20 nm process technology, a low 0.9 V core power supply, an enhanced core architecture, and several optional power reduction techniques to reduce total power consumption by as much as 40% compared to Arria V devices and as much as 60% compared to Stratix V devices.

⁽¹³⁾ Enabling either compression or design security features affects the maximum data rate. Refer to the Intel Arria 10 Device Datasheet for more information.

⁽¹⁴⁾ Encryption and compression cannot be used simultaneously.

⁽¹⁵⁾ Partial reconfiguration is an advanced feature of the device family. If you are interested in using partial reconfiguration, contact Intel for support.

⁽¹⁷⁾ Supported at a maximum clock rate of 100 MHz.



The optional power reduction techniques in Intel Arria 10 devices include:

- SmartVID—a code is programmed into each device during manufacturing that allows a smart regulator to operate the device at lower core V_{CC} while maintaining performance
- **Programmable Power Technology**—non-critical timing paths are identified by the Intel Quartus Prime software and the logic in these paths is biased for low power instead of high performance
- **Low Static Power Options**—devices are available with either standard static power or low static power while maintaining performance

Furthermore, Intel Arria 10 devices feature Intel's industry-leading low power transceivers and include a number of hard IP blocks that not only reduce logic resources but also deliver substantial power savings compared to soft implementations. In general, hard IP blocks consume up to 90% less power than the equivalent soft logic implementations.

Incremental Compilation

The Intel Quartus Prime software incremental compilation feature reduces compilation time and helps preserve performance to ease timing closure. The incremental compilation feature enables the partial reconfiguration flow for Intel Arria 10 devices.

Incremental compilation supports top-down, bottom-up, and team-based design flows. This feature facilitates modular, hierarchical, and team-based design flows where different designers compile their respective design sections in parallel. Furthermore, different designers or IP providers can develop and optimize different blocks of the design independently. These blocks can then be imported into the top level project.

Document Revision History for Intel Arria 10 Device Overview

Document Version		Changes
	2018.04.09	Updated the lowest V_{CC} from 0.83 V to 0.82 V in the topic listing a summary of the device features.

Date	Version	Changes
January 2018	2018.01.17	Updated the maximum data rate for HPS (Intel Arria 10 SX devices external memory interface DDR3 controller from 2,166 Mbps to 2,133 Mbps.
		Updated maximum frequency supported for half rate QDRII and QDRII + SRAM to 633 MHz in Memory Standards Supported by the Soft Memory Controller table.
		Updated transceiver backplane capability to 12.5 Gbps.
		Removed transceiver speed grade 5 in Sample Ordering Core and Available Options for Intel Arria 10 GX Devices figure.
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